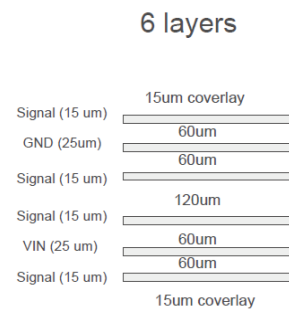


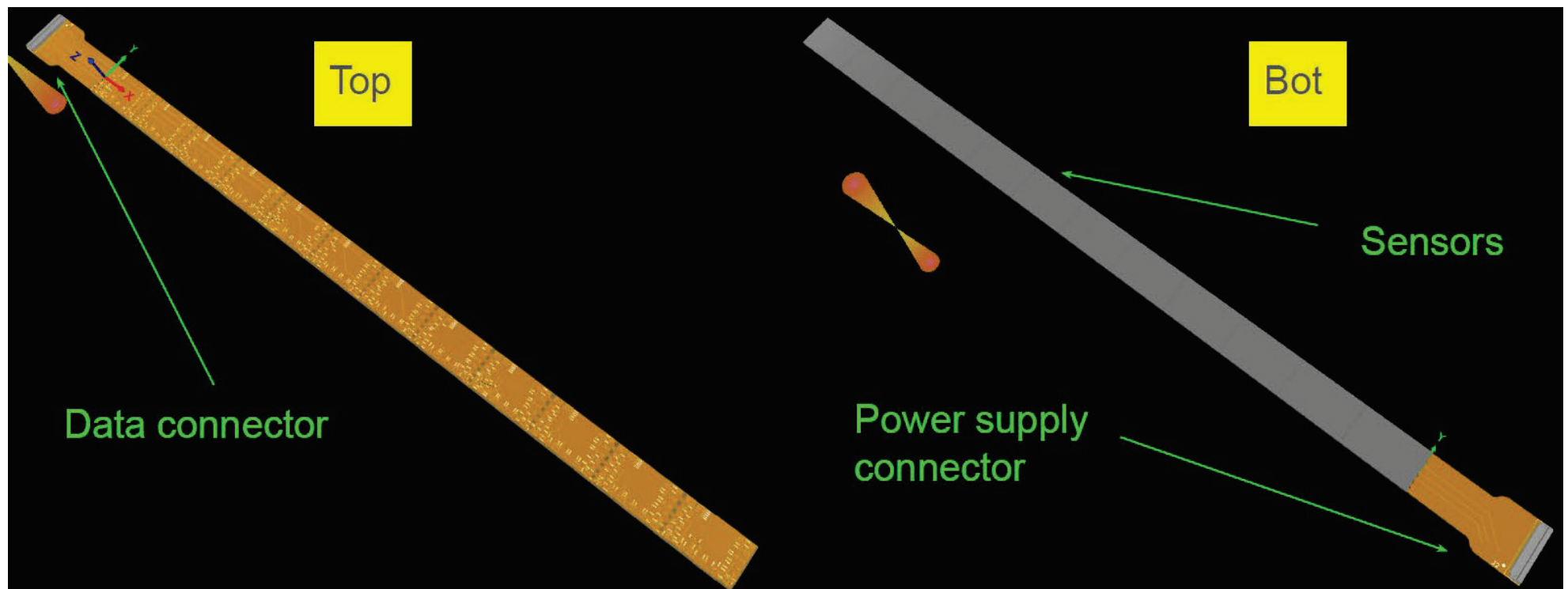
L6 Al-Flex layer stack-up



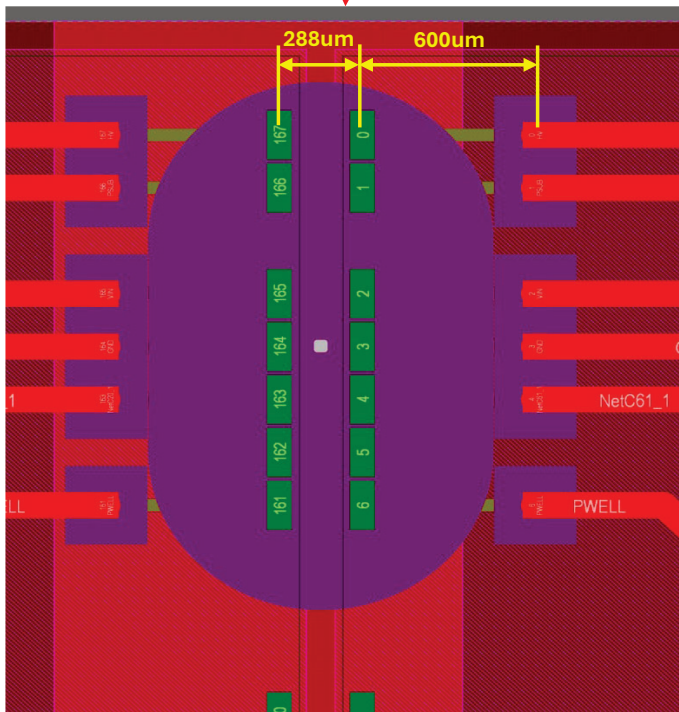
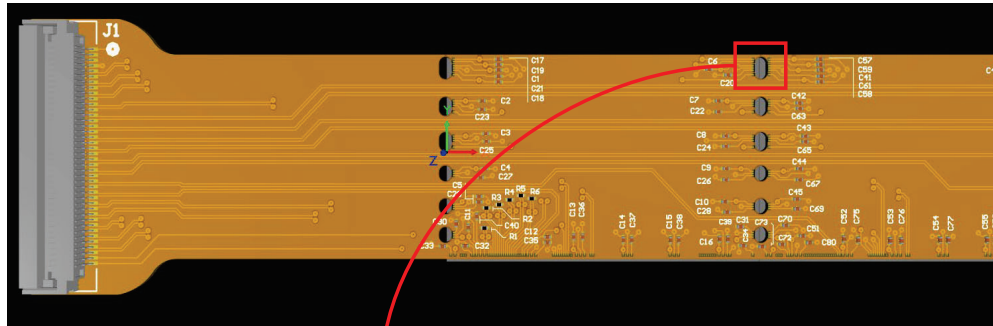
#	Name	Material	Type	Thickness	Weight	Dk	Df
	Top Overlay 1		Overlay				
	Top Solder 1	Coverlay	Solder Mask	30µm		4.6	0.072
1	Signal1		Signal	15µm	1/2oz		
	Dielectric 1	polyimide bond/ply	Prepreg	60µm		3.3	0.002
2	GND		Signal	25µm	1/2oz		
	Dielectric 4	polyimide bond/ply	Prepreg	60µm		3.3	0.002
3	Signal2		Signal	15µm	1/2oz		
	Dielectric 3	polymide+thermoplastic poly	Core	120µm		3.3	0.002
4	Signal3		Signal	15µm	1/2oz		
	Dielectric 5	polyimide bond/ply	Prepreg	60µm		3.3	0.002
5	VIN		Signal	25µm	1/2oz		
	Dielectric 2	polyimide bond/ply	Prepreg	60µm		3.3	0.002
6	Signal4		Signal	15µm	1/2oz		
	Bottom Solder 1	Coverlay	Solder Mask	30µm		4.6	0.072
	Bottom Overlay 1		Overlay				

- Flex thickness 530um
- Ni/Au plating on the bonding pads and component pads (CERN specs)

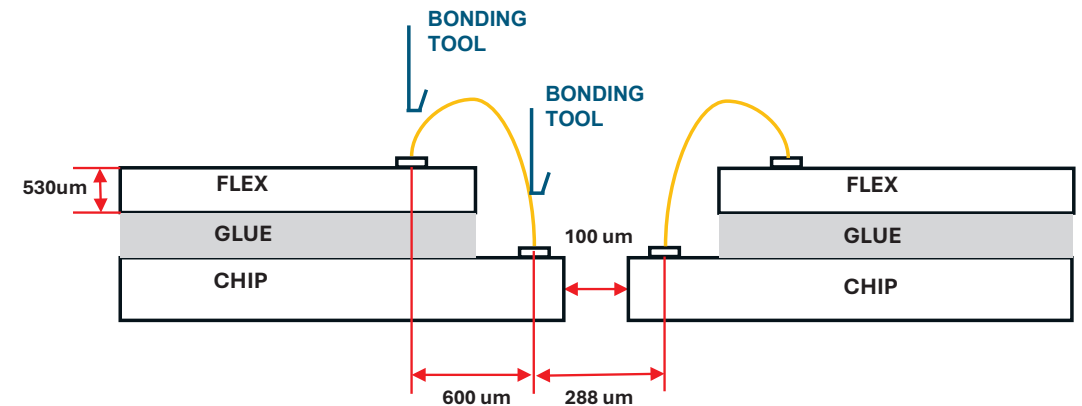
L6 flex – 3D view



L6 flex – Top



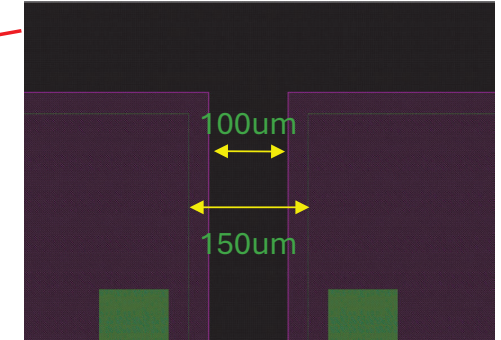
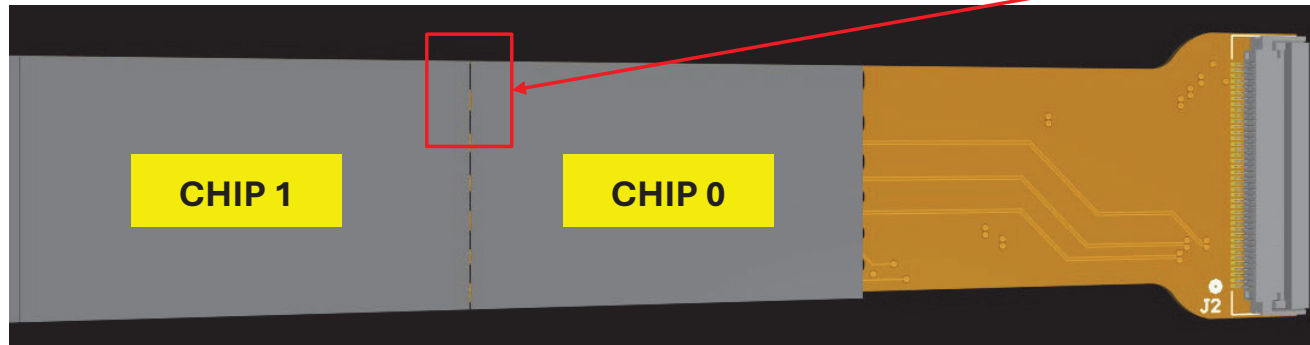
- Flex thickness 530um
- Ni/Au plating on the bonding pads and component pads
- Chip pad: 88umx188um
- Flex pad: 88umx100um
- Slot size: 1.2mmx2mm/1.2mmx1.7mm/1.2mmx1.4mm





- Flex thickness 530um
- Ni/Au plating on the bonding pads and component pads
- Chip pad: 88umx188um
- Flex pad: 88umx100um
- Slot size: 1.2mmx2mm/1.2mmx1.7mm/1.2mmx1.4mm

L6 flex – Bottom



- The distance between seal ring and chip edge is 25um